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### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	16MHz
Connectivity	CANbus, I <sup>2</sup> C, IEBus, SIO, UART/USART
Peripherals	DMA, POR, PWM, Voltage Detect, WDT
Number of I/O	71
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 27x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/m30290fcvhp-u7a">https://www.e-xfl.com/product-detail/renesas-electronics-america/m30290fcvhp-u7a</a>

## Notice

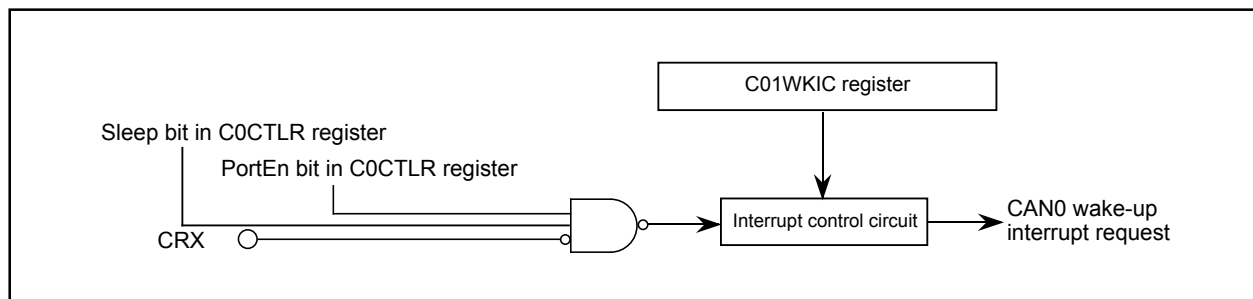
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## 9.9 CAN0 Wake-up Interrupt

CAN0 wake-up interrupt occurs when a falling edge is input to CRX. The CAN0 wake-up interrupt is enabled when the PortEn bit is set to 1 (CTX/CRX function) and Sleep bit is set to 1 (Sleep mode enabled) in the C0CTLR register. **Figure 9.13** shows the block diagram of the CAN0 wake-up interrupt.



**Figure 9.13 CAN0 Wake-up Interrupt Block Diagram**

## 9.10 Address Match Interrupt

An address match interrupt request is generated immediately before executing the instruction at the address indicated by the RMADi register (i=0 to 1). Set the start address of any instruction in the RMADi register. Use bits AIER1 and AIER0 in the AIER register to enable or disable the interrupt. Note that the address match interrupt is unaffected by the I flag and IPL. For address match interrupts, the value of the PC that is saved to the stack area varies depending on the instruction being executed (refer to “**Saving Registers**”).

(The value of the PC that is saved to the stack area is not the correct return address.) Therefore, follow one of the methods described below to return from the address match interrupt.

- Rewrite the content of the stack and then use the REIT instruction to return.
- Restore the stack to its previous state before the interrupt request was accepted by using the POP or similar other instruction and then use a jump instruction to return.

**Table 9.6** shows the value of the PC that is saved to the stack area when an address match interrupt request is accepted.

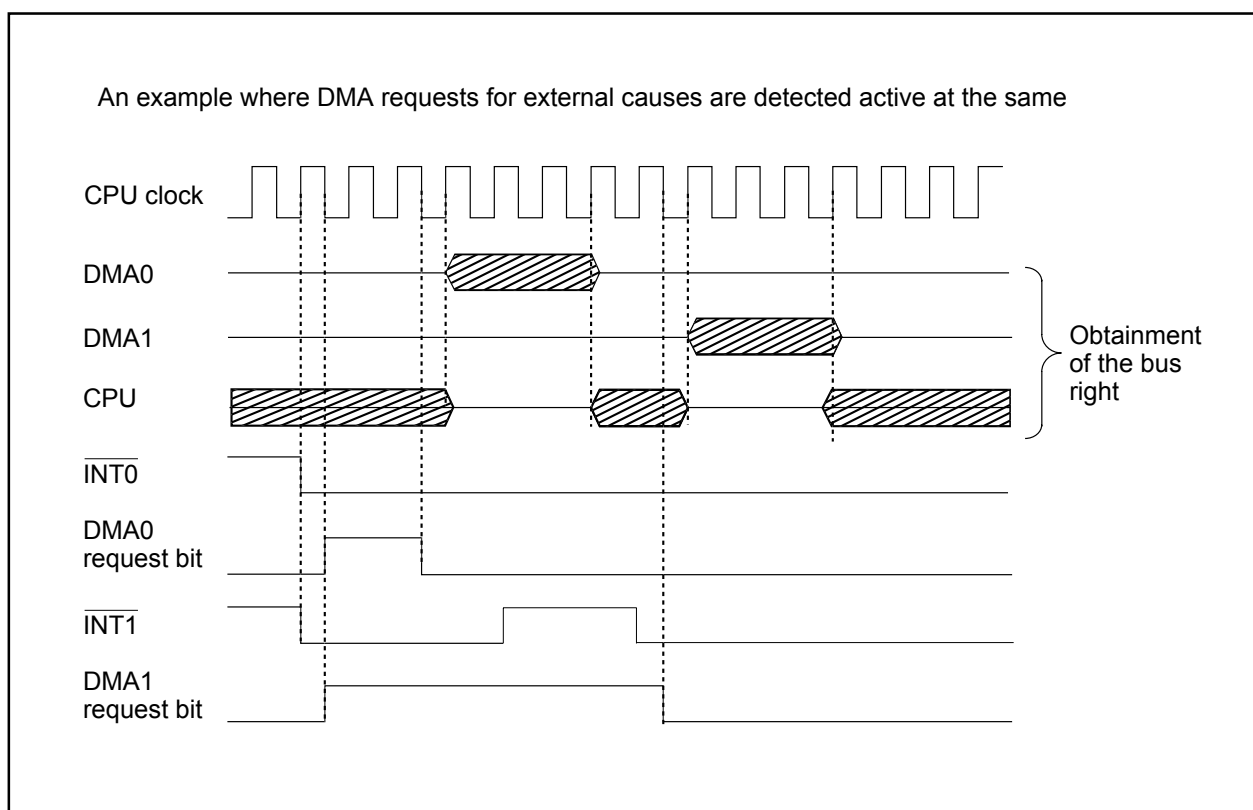
**aFigure 9.14** shows registers AIER, RMAD0, and RMAD1.

## 11.5 Channel Priority and DMA Transfer Timing

If both DMA0 and DMA1 are enabled and DMA transfer request signals from DMA0 and DMA1 are detected active in the same sampling period (one period from a falling edge to the next falling edge of CPU clock), the DMAS bit on each channel is set to 1 (DMA requested) at the same time. In this case, the DMA requests are arbitrated according to the channel priority, DMA0 > DMA1. The following describes DMAC operation when DMA0 and DMA1 requests are detected active in the same sampling period. **Figure 11.6** shows an example of DMA transfer effected by external factors.

DMA0 request having priority is received first to start a transfer when a DMA0 request and DMA1 request are generated simultaneously. After one DMA0 transfer is completed, a bus arbitration is returned to the CPU. When the CPU has completed one bus access, a DMA1 transfer starts. After one DMA1 transfer is completed, the bus arbitration is again returned to the CPU.

In addition, DMA requests cannot be counted up since each channel has one DMAS bit. Therefore, when DMA requests, as DMA1 in **Figure 11.6** occurs more than one time, the DMS bit is set to 0 as soon as getting the bus arbitration. The bus arbitration is returned to the CPU when one transfer is completed.



**Figure 11.6 DMA Transfer by External Factors**

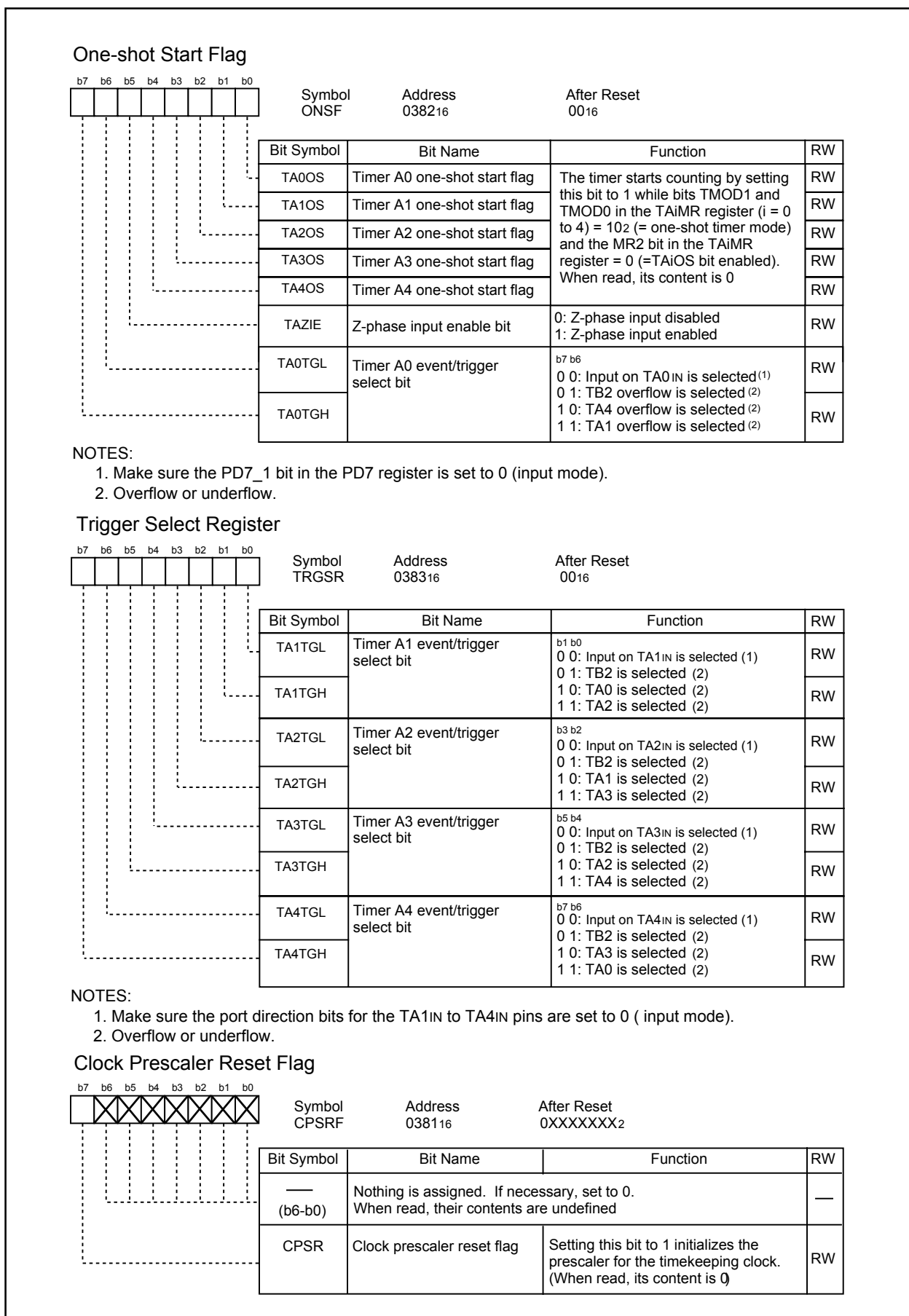


Figure 12.6 ONSF Register, TRGSR Register, and CPSRF Register

### 12.1.2.1 Counter Initialization by Two-Phase Pulse Signal Processing

This function initializes the timer count value to 0 by Z-phase (counter initialization) input during two-phase pulse signal processing.

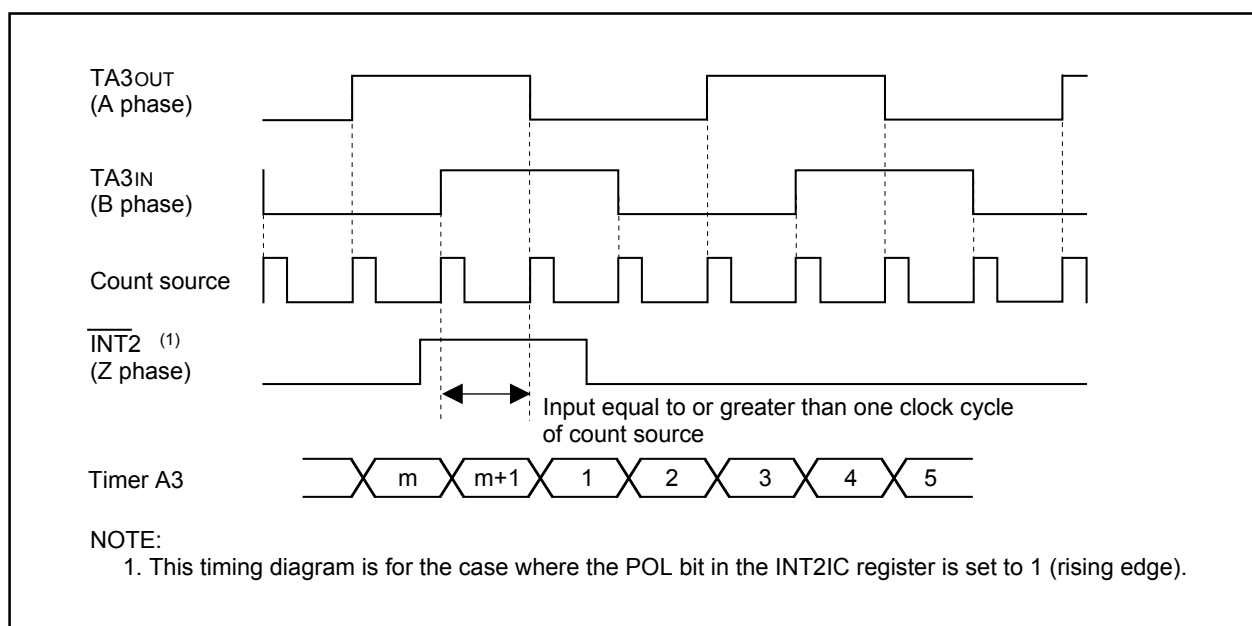
This function can only be used in timer A3 event counter mode during two-phase pulse signal processing, free-running type, x4 processing, with Z-phase entered from the  $\overline{\text{INT2}}$  pin.

Counter initialization by Z-phase input is enabled by writing 0000<sub>16</sub> to the TA3 register and setting the TAZIE bit in ONSF register to 1 (Z-phase input enabled).

Counter initialization is accomplished by detecting Z-phase input edge. The active edge can be chosen to be the rising or falling edge by using the POL bit in the INT2IC register. The Z-phase pulse width applied to the  $\overline{\text{INT2}}$  pin must be equal to or greater than one clock cycle of the timer A3 count source.

The counter is initialized at the next count timing after recognizing Z-phase input. **Figure 12.10** shows the relationship between the two-phase pulse (A phase and B phase) and the Z phase.

If timer A3 overflow or underflow coincides with the counter initialization by Z-phase input, a timer A3 interrupt request is generated twice in succession. Do not use the timer A3 interrupt when using this function.



**Figure 12.10 Two-phase Pulse (A phase and B phase) and the Z Phase**

Figures 13.2 to 13.10 show registers associated with the IC/OC base timer, the time measurement function, and the waveform generating function.

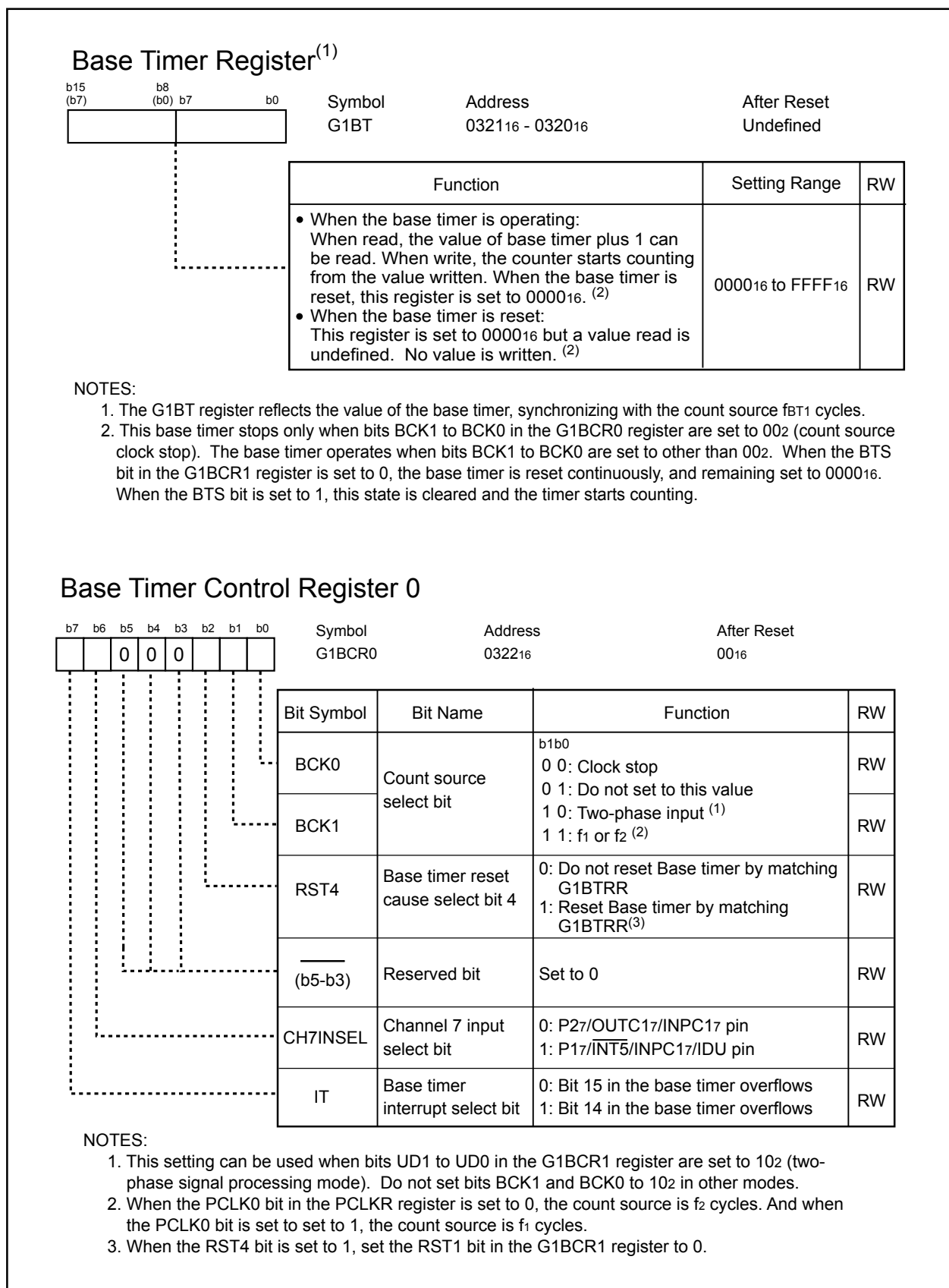


Figure 13.2 G1BT and G1BCR0 Registers

## 13.1 Base Timer

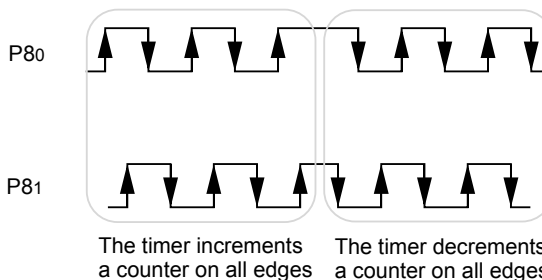
The base timer is a free-running counter that counts an internally generated count source.

**Table 13.2** lists specifications of the base timer. **Table 13.3** shows registers associated with the base timer.

**Figure 13.11** shows a block diagram of the base timer. **Figure 13.12** shows an example of the base timer in counter increment mode. **Figure 13.13** shows an example of the base timer in counter increment/decrement mode. **Figure 13.14** shows an example of two-phase pulse signal processing mode.

**Table 13.2 Base Timer Specifications**

Item	Specification
Count source(fBT1)	f1 or f2 divided by $(n+1)$ , two-phase pulse input divided by $(n+1)$ n: determined by the DIV7 to DIV0 bits in the G1DV register. n=0 to 255 However, no division when n=0
Counting operation	The base timer increments the counter value The base timer increments/decrements the counter value Two-phase pulse signal processing
Count start condition	The BTS bit in the G1BCR1 register is set to 1 (base timer starts counting)
Count stop condition	The BTS bit in the G1BCR1 register is set to 0 (base timer reset)
Base timer reset condition	(1) The value of the base timer matches the value of the G1BTRR register (2) The value of the base timer matches the value of G1PO0 register. (3) Apply a low-level signal ("L") to external interrupt pin, INT1 pin
Value for base timer reset	0000 <sub>16</sub>
Interrupt request	The base timer interrupt request is generated: (1) When the bit 14 or bit 15 in the base timer overflows (2) The value of the base timer value matches the value of the base timer reset register
Read from timer	<ul style="list-style-type: none"> <li>The G1BT register indicates a counter value while the base timer is running</li> <li>The G1BT register is undefined when the base timer is reset</li> </ul>
Write to timer	When a value is written while the base timer is running, the timer counter immediately starts counting from this value. No value can be written while the base timer is reset.
Selectable function	<ul style="list-style-type: none"> <li>Counter increment/decrement mode The base timer starts counting from 0000<sub>16</sub>. After incrementing to FFFF<sub>16</sub>, the timer counter is then decremented back to 0000<sub>16</sub>. The base timer increments the counter value again when the timer counter reaches 0000<sub>16</sub>. (See <b>Figure 13.13</b>)</li> <li>Two-phase pulse processing mode Two-phase pulse signals from pins P80 and P81 are counted (See <b>Figure 13.14</b>)</li> </ul>





### 14.1.6 Special Mode 4 (SIM Mode) (UART2)

Based on UART mode, this is an SIM interface compatible mode. Direct and inverse formats can be implemented, and this mode allows output of a low from the TxD2 pin when a parity error is detected.

**Table 14.18** lists the specifications of SIM mode. **Table 14.19** lists the registers used in the SIM mode and the register values set.

**Table 14.18 SIM Mode Specifications**

Item	Specification
Transfer data format	<ul style="list-style-type: none"> <li>• Direct format</li> <li>• Inverse format</li> </ul>
Transfer clock	<ul style="list-style-type: none"> <li>• The CKDIR bit in the U2MR register is set to 0 (internal clock) : <math>f_i / (16(n+1))</math>  <math>f_i = f_{1SIO}, f_{2SIO}, f_{8SIO}, f_{32SIO}</math>. n: Setting value of U2BRG register 00<sub>16</sub> to FF<sub>16</sub></li> <li>• The CKDIR bit is set to 1 (external clock) : <math>f_{EXT}/16(n+1)</math>  <math>f_{EXT}</math>: Input from CLK2 pin. n: Setting value of U2BRG register 00<sub>16</sub> to FF<sub>16</sub></li> </ul>
Transmission start condition	<ul style="list-style-type: none"> <li>• Before transmission can start, the following requirements must be met <ul style="list-style-type: none"> <li>– The TE bit in the U2C1 register is set to 1 (transmission enabled)</li> <li>– The TI bit in the U2C1 register is set to 0 (data present in U2TB register)</li> </ul> </li> </ul>
Reception start condition	<ul style="list-style-type: none"> <li>• Before reception can start, the following requirements must be met <ul style="list-style-type: none"> <li>– The RE bit in the U2C1 register is set to 1 (reception enabled)</li> <li>– Start bit detection</li> </ul> </li> </ul>
Interrupt request generation timing <sup>(2)</sup>	<ul style="list-style-type: none"> <li>• For transmission When the serial I/O finished sending data from the U2TB transfer register (U2IRS bit =1)</li> <li>• For reception When transferring data from the UART2 receive register to the U2RB register (at completion of reception)</li> </ul>
Error detection	<ul style="list-style-type: none"> <li>• Overrun error <sup>(1)</sup> This error occurs if the serial I/O started receiving the next data before reading the U2RB register and received the bit one before the last stop bit in the the next data</li> <li>• Framing error This error occurs when the number of stop bits set is not detected</li> <li>• Parity error During reception, if a parity error is detected, parity error signal is output from the TxD2 pin. During transmission, a parity error is detected by the level of input to the RxD2 pin when a transmission interrupt occurs</li> <li>• Error sum flag This flag is set to 1 when any of the overrun, framing, and parity errors is encountered</li> </ul>

**NOTES:**

1. If an overrun error occurs, bits 8 to 0 in the U2RB register are undefined. The IR bit in the S2RIC register remains unchanged.
2. A transmit interrupt request is generated by setting the U2IRS bit in the U2C1 register to 1 (transmission complete) and U2ERE bit to 1 (error signal output) after reset. Therefore, when using SIM mode, be sure to clear the IR bit to 0 (no interrupt request) after setting these bits.

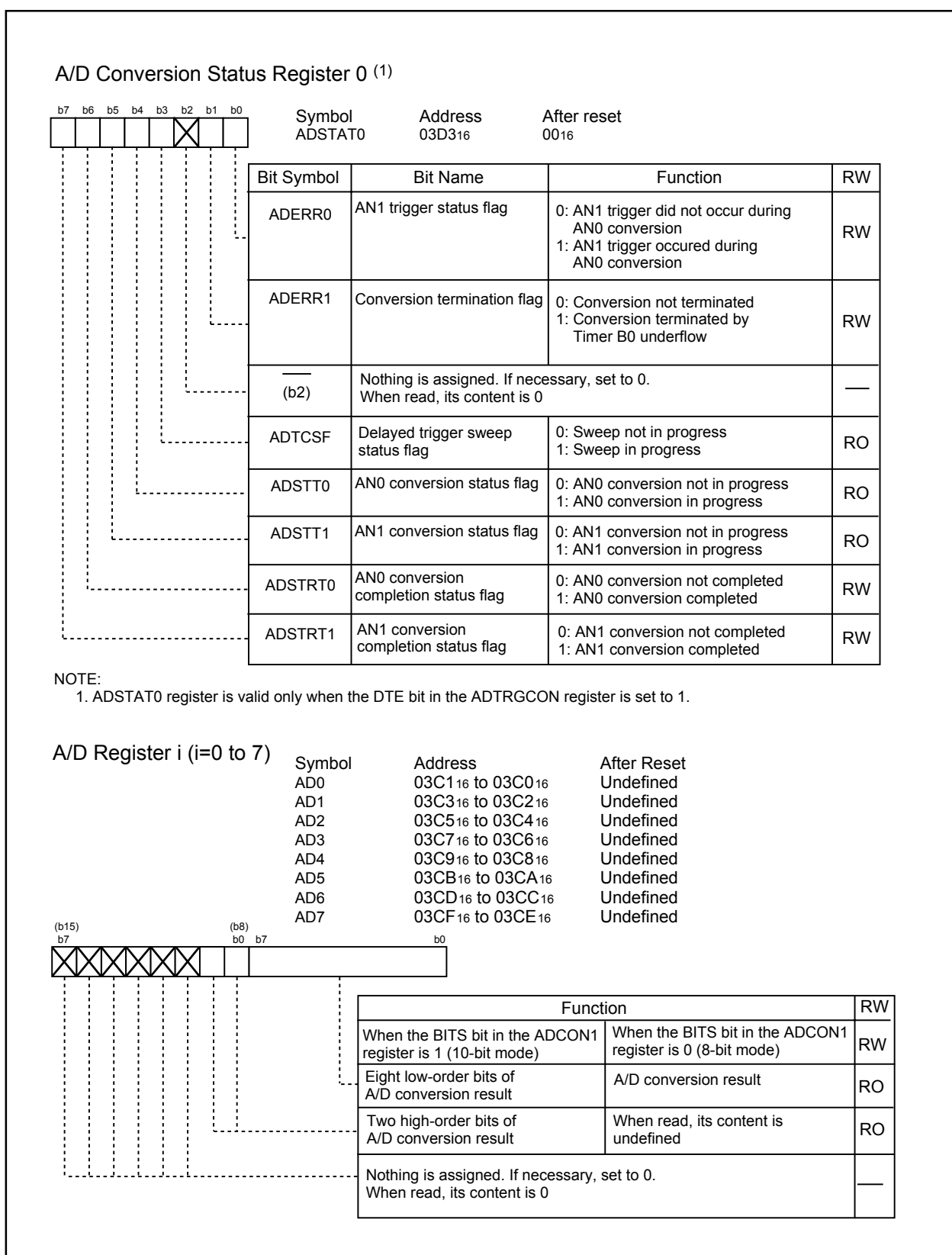
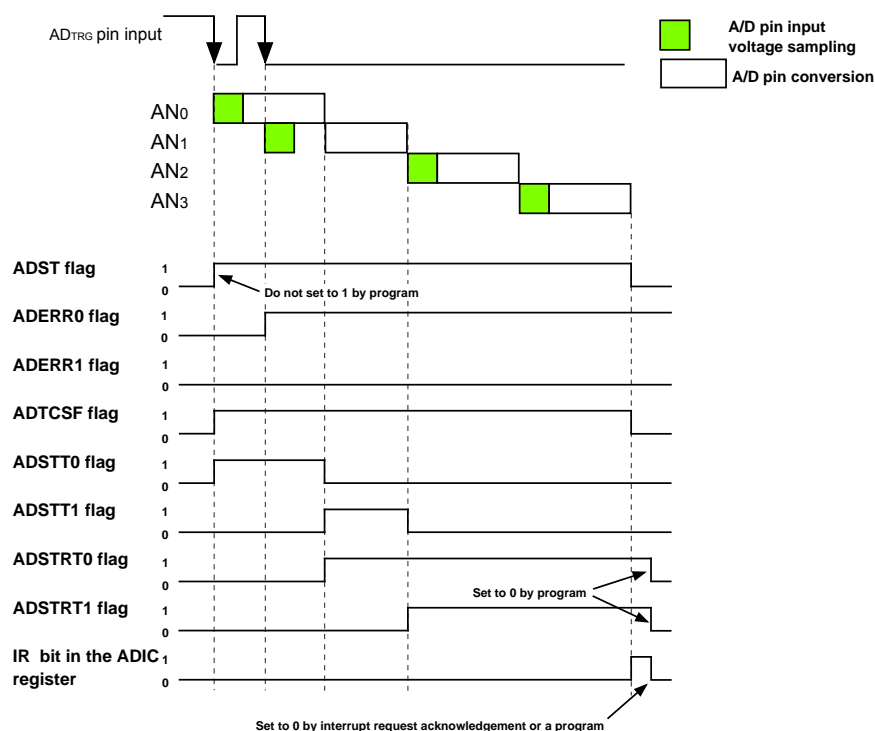


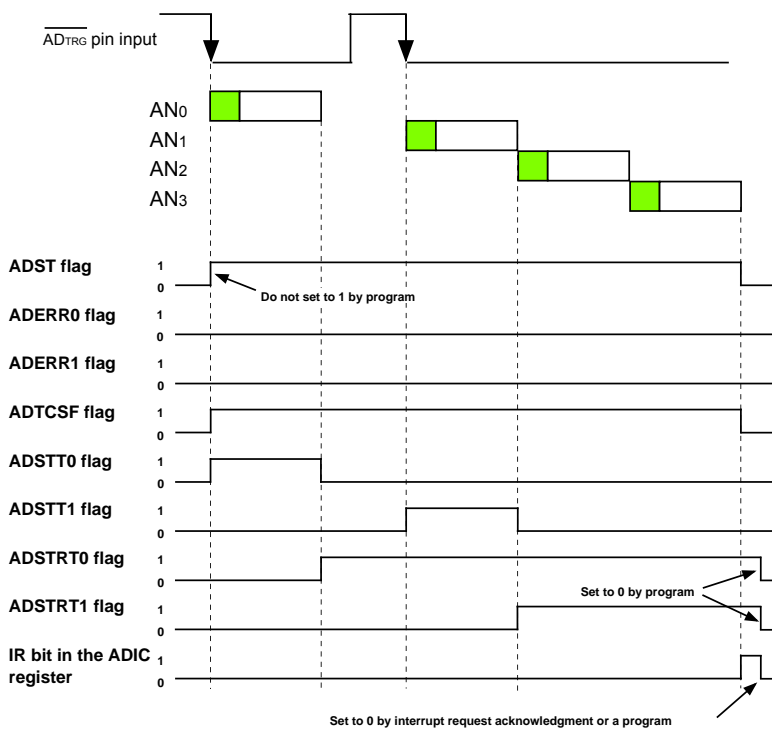
Figure 15.4 ADSTAT0 Register and AD0 to AD7 Registers

•Example when selecting AN0 to AN3 to A/D sweep pins (SCAN1 to SCAN0 = 012)

•Example 1: When ADTRG pin falling edge is generated during AN0 pin conversion



•Example 2: When ADTRG pin falling edge is generated again after AN0 pin conversion



ADST flag: Bit 6 in the ADCON0 register

ADERR0, ADERR1, ADTCSF, ADSTT0, ADSTT1, ADSTR0 and ADSTR1 flag: bits 0, 1, 3, 4, 5, 6 and 7 in the ADSTAT0 register

**Figure 15.25 Each Flag Operation in ADSTAT0 Register Associated with the Operation Example in Delayed Trigger Mode 1 (1)**

### 16.7.1 Bit0: Time-Out Detection Function Enable Bit (TOE)

The TOE bit enables the time-out detection function. When the TOE bit is set to 1, time-out is detected and the I<sup>2</sup>C bus interface interrupt request is generated when the following conditions are met.

- 1) the BB flag in the S10 register is set to 1 (bus busy)
- 2) the SCL clock stops for time-out detection period while high-level ("H") signal is maintained (see

**Table 16.7)**

The internal counter measures the time-out detection time and the TOSEL bit selects between two modes, long time and short time. When time-out is detected, set the ES0 bit to 0 (I<sup>2</sup>C bus interface disabled) and reset the counter.

### 16.7.2 Bit1: Time-Out Detection Flag (TOF )

The TOF flag indicates the time-out detection. If the internal counter which measures the time-out period overflows, the TOF flag is set to 1 and the I<sup>2</sup>C bus interface interrupt request is generated at the same time.

### 16.7.3 Bit2: Time-Out Detection Period Select Bit (TOSEL)

The TOSEL bit selects time-out detection period from long time mode and short time mode. When the TOSEL bit is set to 0, long time mode is selected. When it is set to 1, short time mode is selected, respectively. The internal counter increments as a 16-bit counter in long time mode, while the counter increments as a 14-bit counter in short time mode, based on the I<sup>2</sup>C system clock (V<sub>IIC</sub>) as a counter source. **Table 16.7** shows examples of time-out detection period.

**Table 16.7 Examples of Time-out Detection Period (Unit: ms)**

V <sub>IIC</sub> (MHz)	Long time mode	Short time mode
4	16.4	4.1
2	32.8	8.2
1	65.6	16.4

### 16.7.4 Bits 3,4,5: I<sup>2</sup>C System Clock Select Bits (ICK2-4)

Bits ICK4 to ICK2, and bits ICK1 and ICK0 in the S3D0 register, and the PCLK0 bit in the PCLKR register select the system clock (V<sub>IIC</sub>) of the I<sup>2</sup>C bus interface circuit. See **Table 16.6** for the setting values.

### 16.7.5 Bit7: STOP Condition Detection Interrupt Request Bit (SCPIN)

The SCPIN bit monitors the stop condition detection interrupt. The SCPIN bit is set to 1 when the I<sup>2</sup>C bus interface interrupt is generated by detecting the STOP condition. When this bit is set to 0 by program, it becomes 0. However, no change occurs even if it is set to 1.

## 17.2 Operating Modes

The CAN module has the following four operating modes.

- CAN Reset/Initialization Mode
- CAN Operating Mode
- CAN Sleep Mode
- CAN Interface Sleep Mode

Figure 17.17 shows transition between operating modes.

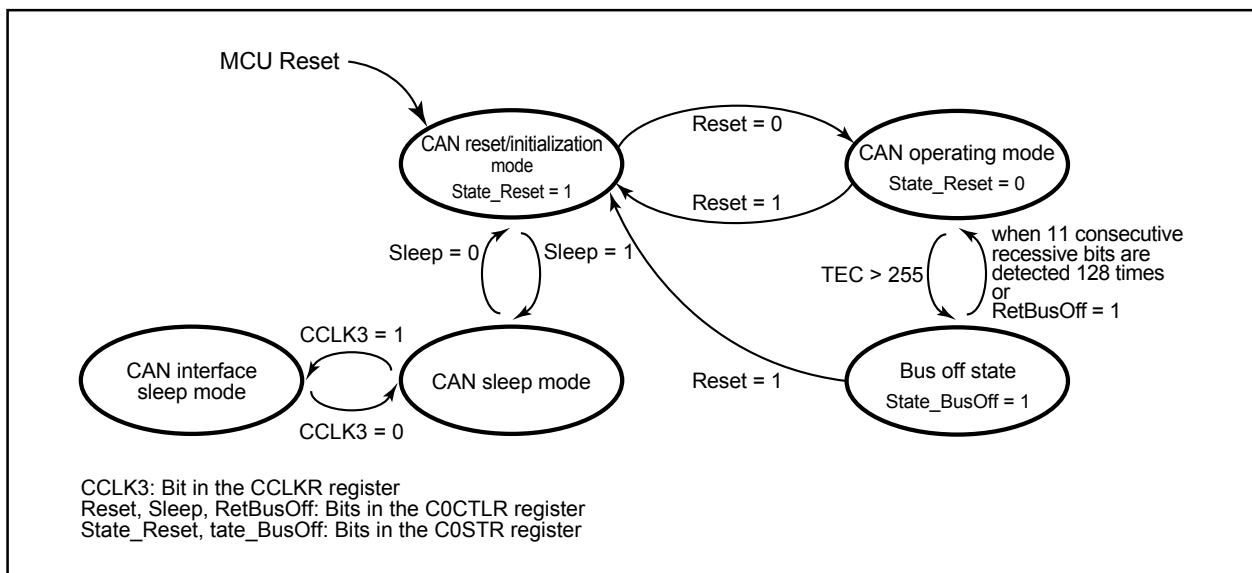


Figure 17.17 Transition Between Operating Modes

### 17.2.1 CAN Reset/Initialization Mode

The CAN reset/initialization mode is activated upon MCU reset or by setting the Reset bit in the C0CTLR register to 1. If the Reset bit is set to 1, check that the State\_Reset bit in the C0STR register is set to 1. Entering the CAN reset/initialization mode initiates the following functions by the module:

- CAN communication is impossible.
- When the CAN reset/initialization mode is activated during an ongoing transmission in operation mode, the module suspends the mode transition until completion of the transmission (successful, arbitration loss, or error detection). Then, the State\_Reset bit is set to 1, and the CAN reset/initialization mode is activated.
- Registers C0MCTLj (j = 0 to 15), C0STR, C0ICR, C0IDR, C0RECR, C0TECR, and C0TSR are initialized. All these registers are locked to prevent CPU modification.
- Registers C0CTLR, C0CONR, C0GMR, C0LMAR, and C0LMBR and the CAN0 message box retain their contents and are available for CPU access.

## 18. CRC Calculation Circuit

The Cyclic Redundancy Check (CRC) calculation detects errors in blocks of data. The MCU uses a generator polynomial of CRC\_CCITT ( $X^{16} + X^{12} + X^5 + 1$ ) or CRC-16 ( $X^{16} + X^{15} + X^2 + 1$ ) to generate CRC code.

The CRC code is a 16-bit code generated for a block of a given data length in multiples of bytes. The code is updated in the CRC data register everytime one byte of data is transferred to a CRC input register. The data register must be initialized before use. Generation of CRC code for one byte of data is completed in two machine cycles.

**Figure 18.1** shows the block diagram of the CRC circuit. **Figure 18.2** shows the CRC-related registers. **Figure 18.3** shows the calculation example using the CRC\_CCITT operation.

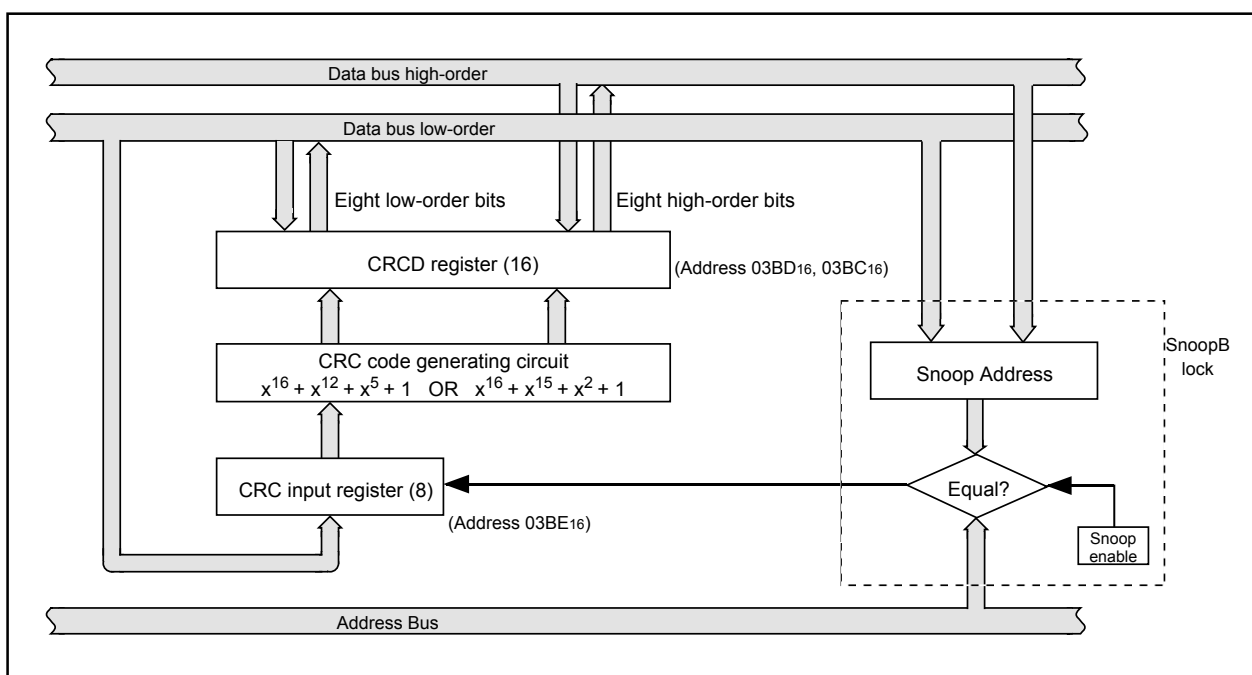
### 18.1 CRC Snoop

The CRC circuit includes the ability to snoop reads and writes to certain SFR addresses. This can be used to accumulate the CRC value on a stream of data without using extra bandwidth to explicitly write data into the CRCIN register. All SFR addresses after 0020<sub>16</sub> are subject to the CRC snoop. The CRC snoop is useful to snoop the writes to a UART TX buffer, or the reads from a UART RX buffer.

To snoop an SFR address, the target address is written to the CRC snoop Address Register (CRCSAR). The two most significant bits of this register enable snooping on reads or writes to the target address. If the target SFR is written to by the CPU or DMA, and the CRC snoop write bit is set (CRCSW=1), the CRC will latch the data into the CRCIN register. The new CRC code will be set in the CRCD register.

Similarly, if the target SFR is read by the CRC or DMA, and the CRC snoop read bit is set (CRCSR=1), the CRC will latch the data from the target into the CRCIN register and calculate the CRC.

The CRC circuit can only calculate CRC codes on data byte at a time. Therefore, if a target SFR is accessed in word (16 bit), only one low-order byte data is stored into the CRCIN register.



**Figure 18.1** CRC circuit block diagram

## 19.5 Pin Assignment Control Register (PACR)

**Figure 19.10** shows the PACR register. After reset, set bits PACR2 to PACR0 in the PACR register before a signal is input or output to each pin. When bits PACR2 to PACR0 are not set, some pins do not function as I/O ports.

Bits PACR2 to PACR0: control pins to be used

Value after reset: 0002.

To select the 80-pin package, set the bits to 0112.

To select the 64-pin package, set the bits to 0102.

U1MAP bit: controls pin assignments for the UART1 function.

To assign the UART1 function to P64/ $\overline{\text{CTS1}}$ / $\overline{\text{RTS1}}$ , P65/CLK1, P66/RxD1, and P67/TxD1, set the U1MAP bit to 0 (P67 to P64).

To assign the function to P70/ $\overline{\text{CTS1}}$ / $\overline{\text{RTS1}}$ , P71/CLK1, P72/RxD1, and P73/TxD1, set the U1MAP bit to 1 (P73 to P70)

The PRC2 bit in the PRCR protects the PACR register. Set the PACR register after setting the PRC2 bit in the PRCR register.

## 19.6 Digital Debounce Function

Two digital debounce function circuits are provided. Level is determined when level is held, after applying either a falling edge or rising edge to the pin, longer than the programmed filter width time. This enables noise reduction.

This function is assigned to  $\overline{\text{INT5}}$ / $\overline{\text{INPC17}}$  and  $\overline{\text{NMI}}$ / $\overline{\text{SD}}$ . Digital filter width is set in the NDDR register and the P17DDR register respectively. **Figure 19.11** shows the NDDR register and the P17DDR register. Additionally, a digital debounce function is disabled to the port P17 input and the port P85 input.

Filter width :  $(n+1) \times 1/f_8$       n: count value set in the NDDR register and P17DDR register

The NDDR register and the P17DDR register decrement count value with  $f_8$  as the count source. The NDDR register and the P17DDR register indicate count time. Count value is reloaded if a falling edge or a rising edge is applied to the pin.

The NDDR register and the P17DDR register can be set 00<sub>16</sub> to FF<sub>16</sub> when using the digital debounce function. Setting to FF<sub>16</sub> disables the digital filter. See **Figure 19.12** for details.

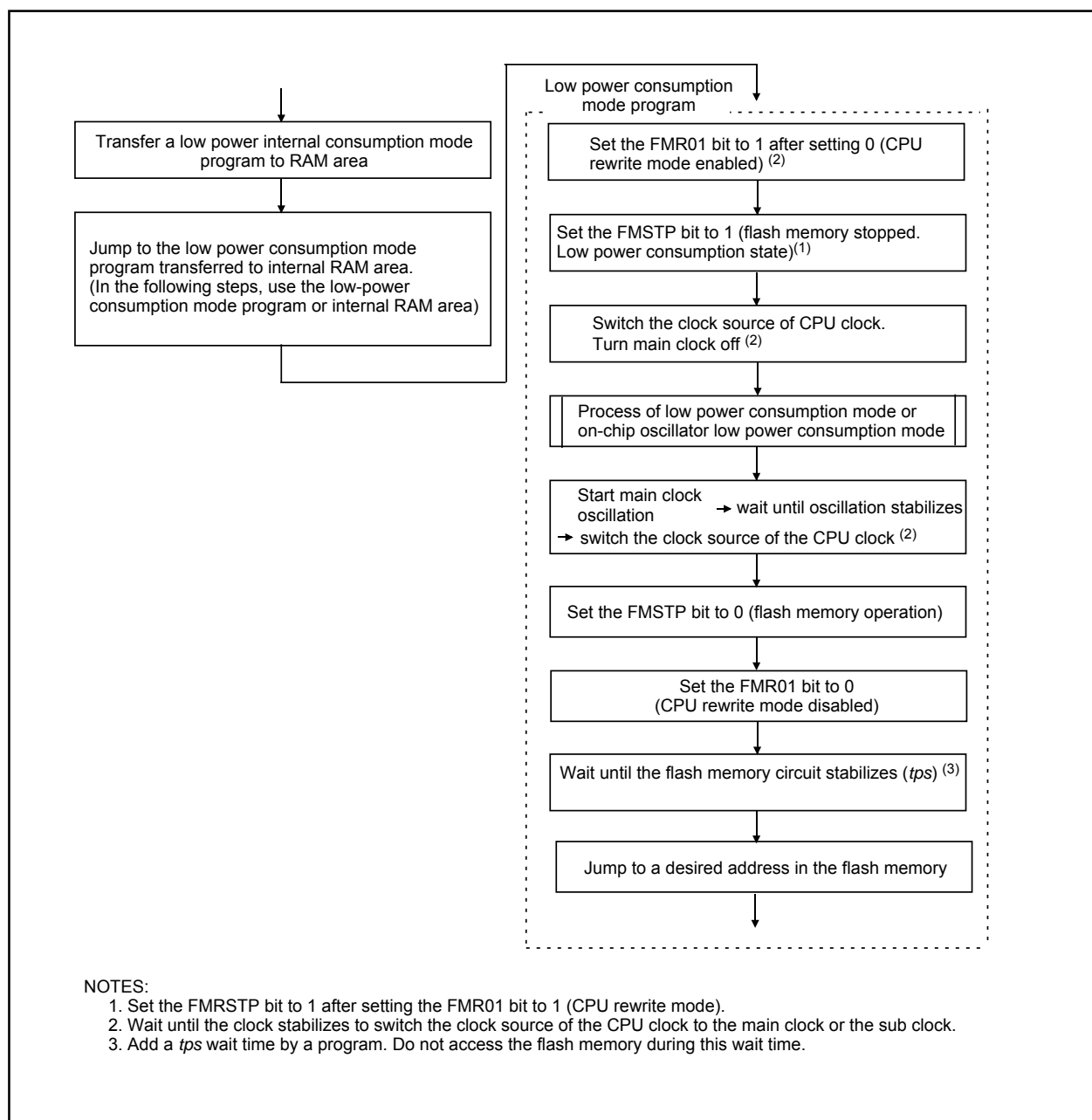


Figure 20.10 Processing Before and After Low Power Dissipation Mode



**V<sub>CC</sub> = 3V****Table 21.24 Electrical Characteristics (Note 1)**

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V <sub>OH</sub>	Output High ("H") Voltage	P0 <sub>0</sub> to P0 <sub>7</sub> , P1 <sub>0</sub> to P1 <sub>7</sub> , P2 <sub>0</sub> to P2 <sub>7</sub> , P3 <sub>0</sub> to P3 <sub>7</sub> , P6 <sub>0</sub> to P6 <sub>7</sub> , P7 <sub>0</sub> to P7 <sub>7</sub> , P8 <sub>0</sub> to P8 <sub>7</sub> , P9 <sub>0</sub> to P9 <sub>3</sub> , P9 <sub>5</sub> to P9 <sub>7</sub> , P10 <sub>0</sub> to P10 <sub>7</sub>	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> -0.5		V <sub>CC</sub>	V
V <sub>OH</sub>	Output High ("H") Voltage	X <sub>OUT</sub>	High Power	I <sub>OH</sub> = -0.1 mA	V <sub>CC</sub> -0.5	V <sub>CC</sub>	V
			Low Power	I <sub>OH</sub> = -50 μA	V <sub>CC</sub> -0.5	V <sub>CC</sub>	
	Output High ("H") Voltage	X <sub>COU</sub>	High Power	No load applied		2.5	V
			Low Power	No load applied		1.6	
V <sub>OL</sub>	Output Low ("L") Voltage	P0 <sub>0</sub> to P0 <sub>7</sub> , P1 <sub>0</sub> to P1 <sub>7</sub> , P2 <sub>0</sub> to P2 <sub>7</sub> , P3 <sub>0</sub> to P3 <sub>7</sub> , P6 <sub>0</sub> to P6 <sub>7</sub> , P7 <sub>0</sub> to P7 <sub>7</sub> , P8 <sub>0</sub> to P8 <sub>7</sub> , P9 <sub>0</sub> to P9 <sub>3</sub> , P9 <sub>5</sub> to P9 <sub>7</sub> , P10 <sub>0</sub> to P10 <sub>7</sub>	I <sub>OL</sub> = 1 mA			0.5	V
V <sub>OL</sub>	Output Low ("L") Voltage	X <sub>OUT</sub>	High Power	I <sub>OL</sub> = 0.1 mA		0.5	V
			Low Power	I <sub>OL</sub> = 50 μA		0.5	
	Output Low ("L") Voltage	X <sub>COU</sub>	High Power	No load applied		0	V
			Low Power	No load applied		0	
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis	TA0 <sub>IN</sub> -TA4 <sub>IN</sub> , TB0 <sub>IN</sub> -TB2 <sub>IN</sub> , INT <sub>0</sub> -INT <sub>5</sub> , NMI, AD <sub>TRG</sub> , CTS <sub>0</sub> -CTS <sub>2</sub> , SCL, SDA, CLK <sub>0</sub> -CLK <sub>2</sub> , TA2 <sub>OUT</sub> -TA4 <sub>OUT</sub> , KI <sub>0</sub> -KI <sub>3</sub> , R <sub>XD0</sub> -R <sub>XD2</sub> , S <sub>IN3</sub> , S <sub>IN4</sub>				0.8	V
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis	RESET				1.8	V
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis	X <sub>IN</sub>				0.8	V
I <sub>IH</sub>	Input High ("H") Current	P0 <sub>0</sub> to P0 <sub>7</sub> , P1 <sub>0</sub> to P1 <sub>7</sub> , P2 <sub>0</sub> to P2 <sub>7</sub> , P3 <sub>0</sub> to P3 <sub>7</sub> , P6 <sub>0</sub> to P6 <sub>7</sub> , P7 <sub>0</sub> to P7 <sub>7</sub> , P8 <sub>0</sub> to P8 <sub>7</sub> , P9 <sub>0</sub> to P9 <sub>3</sub> , P9 <sub>5</sub> to P9 <sub>7</sub> , P10 <sub>0</sub> to P10 <sub>7</sub> X <sub>IN</sub> , RESET, CNV <sub>SS</sub>	V <sub>I</sub> = 3 V			4.0	μA
I <sub>IL</sub>	Input Low ("L") Current	P0 <sub>0</sub> to P0 <sub>7</sub> , P1 <sub>0</sub> to P1 <sub>7</sub> , P2 <sub>0</sub> to P2 <sub>7</sub> , P3 <sub>0</sub> to P3 <sub>7</sub> , P6 <sub>0</sub> to P6 <sub>7</sub> , P7 <sub>0</sub> to P7 <sub>7</sub> , P8 <sub>0</sub> to P8 <sub>7</sub> , P9 <sub>0</sub> to P9 <sub>3</sub> , P9 <sub>5</sub> to P9 <sub>7</sub> , P10 <sub>0</sub> to P10 <sub>7</sub> X <sub>IN</sub> , RESET, CNV <sub>SS</sub>	V <sub>I</sub> = 0 V			-4.0	μA
R <sub>PULLUP</sub>	Pull-up Resistance	P0 <sub>0</sub> to P0 <sub>7</sub> , P1 <sub>0</sub> to P1 <sub>7</sub> , P2 <sub>0</sub> to P2 <sub>7</sub> , P3 <sub>0</sub> to P3 <sub>7</sub> , P6 <sub>0</sub> to P6 <sub>7</sub> , P7 <sub>0</sub> to P7 <sub>7</sub> , P8 <sub>0</sub> to P8 <sub>7</sub> , P9 <sub>0</sub> to P9 <sub>3</sub> , P9 <sub>5</sub> to P9 <sub>7</sub> , P10 <sub>0</sub> to P10 <sub>7</sub>	V <sub>I</sub> = 0 V	50	100	500	kΩ
R <sub>fXIN</sub>	Feedback Resistance	X <sub>IN</sub>			3.0		MΩ
R <sub>fXCIN</sub>	Feedback Resistance	X <sub>CIN</sub>			25		MΩ
V <sub>RAM</sub>	RAM Standby Voltage		In stop mode	2.0			V

NOTE:

1. Referenced to V<sub>CC</sub> = 2.7 to 3.6 V, V<sub>SS</sub> = 0 V at Topr = -20 to 85 °C / -40 to 85 °C, f(BCLK) = 10MHz unless otherwise specified.

$$V_{CC} = 3V$$

**Timing Requirements**

( $V_{CC} = 3V$ ,  $V_{SS} = 0V$ , at  $T_{opr} = -20$  to  $85^{\circ}C$  /  $-40$  to  $85^{\circ}C$  unless otherwise specified)

**Table 21.26 External Clock Input (XIN input)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c$	External clock input cycle time	100		ns
$t_{w(H)}$	External clock input HIGH pulse width	40		ns
$t_{w(L)}$	External clock input LOW pulse width	40		ns
$t_r$	External clock rise time		18	ns
$t_f$	External clock fall time		18	ns

$$V_{CC} = 3V$$

### Timing Requirements

( $V_{CC} = 3V$ ,  $V_{SS} = 0V$ , at  $T_{op} = -20$  to  $85^{\circ}C$  /  $-40$  to  $85^{\circ}C$  unless otherwise specified)

**Table 21.33 Timer B Input (Counter Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIn input cycle time (counted on one edge)	150		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width (counted on one edge)	60		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width (counted on one edge)	60		ns
$t_{c(TB)}$	TBiIn input cycle time (counted on both edges)	300		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width (counted on both edges)	120		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width (counted on both edges)	120		ns

**Table 21.34 Timer B Input (Pulse Period Measurement Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIn input cycle time	600		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width	300		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width	300		ns

**Table 21.35 Timer B Input (Pulse Width Measurement Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIn input cycle time	600		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width	300		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width	300		ns

**Table 21.36 A/D Trigger Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(AD)}$	$\overline{ADTRG}$ input cycle time (trigger able minimum)	1500		ns
$t_{w(ADL)}$	$\overline{ADTRG}$ input LOW pulse width	200		ns

**Table 21.37 Serial I/O**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	150		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	150		ns
$t_d(C-Q)$	TxDi output delay time		160	ns
$t_h(C-Q)$	TxDi hold time	0		ns
$t_{su}(D-C)$	RxDi input setup time	100		ns
$t_h(C-D)$	RxDi input hold time	90		ns

**Table 21.38 External Interrupt  $\overline{INTi}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input HIGH pulse width	380		ns
$t_{w(INL)}$	$\overline{INTi}$ input LOW pulse width	380		ns

$$V_{CC} = 3V$$

### Timing Requirements

( $V_{CC} = 3V$ ,  $V_{SS} = 0V$ , at  $T_{opr} = -40$  to  $85^{\circ}C$  unless otherwise specified)

**Table 21.71 Timer B Input (Counter Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIn input cycle time (counted on one edge)	150		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width (counted on one edge)	60		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width (counted on one edge)	60		ns
$t_{c(TB)}$	TBiIn input cycle time (counted on both edges)	300		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width (counted on both edges)	120		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width (counted on both edges)	120		ns

**Table 21.72 Timer B Input (Pulse Period Measurement Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIn input cycle time	600		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width	300		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width	300		ns

**Table 21.73 Timer B Input (Pulse Width Measurement Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIn input cycle time	600		ns
$t_{w(TBH)}$	TBiIn input HIGH pulse width	300		ns
$t_{w(TBL)}$	TBiIn input LOW pulse width	300		ns

**Table 21.74 A/D Trigger Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(AD)}$	ADTRG input cycle time (trigger able minimum)	1500		ns
$t_{w(ADL)}$	ADTRG input LOW pulse width	200		ns

**Table 21.75 Serial I/O**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	150		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	150		ns
$t_{d(C-Q)}$	TxDi output delay time		160	ns
$t_{h(C-Q)}$	TxDi hold time	0		ns
$t_{su(D-C)}$	RxDi input setup time	100		ns
$t_{h(C-D)}$	RxDi input hold time	90		ns

**Table 21.76 External Interrupt INTi Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	INTi input HIGH pulse width	380		ns
$t_{w(INL)}$	INTi input LOW pulse width	380		ns

## 22.12 Programmable I/O Ports

1. If a low-level signal is applied to the  $\overline{SD}$  pin when the IVPCR1 bit in the TB2SC register is set to 1 (three-phase output forcible cutoff by input on  $\overline{SD}$  pin enabled), the P72 to P75, P80 and P81 pins go to a high-impedance state.
2. The input threshold voltage of pins differs between programmable input/output ports and peripheral functions.  
Therefore, if any pin is shared by a programmable input/output port and a peripheral function and the input level at this pin is outside the range of recommended operating conditions  $V_{IH}$  and  $V_{IL}$  (neither "high" nor "low"), the input level may be determined differently depending on which side—the programmable input/output port or the peripheral function—is currently selected.
3. When the SM32 bit in the S3C register is set to 1, the P32 pin goes to high-impedance state. When the SM42 bit in the S4C register is set to 1, the P96 pin goes to high-impedance state.
4. When the INV03 bit in the INVC0 register is 1 (three-phase motor control timer output enabled), an "L" input on the P85  $\overline{NMI}/\overline{SD}$  pin, has the following effect.

- When the TB2SC register IVPCR1 bit is set to 1 (three-phase output forcible cutoff by input on  $\overline{SD}$  pin enabled), the U/  $\overline{U}$ / V/  $\overline{V}$ / W/  $\overline{W}$  pins go to a high-impedance state.
- When the TB2SC register IVPCR1 bit is set to 0 (three-phase output forcible cutoff by input on  $\overline{SD}$  pin disabled), the U/  $\overline{U}$ / V/  $\overline{V}$ / W/  $\overline{W}$  pins go to a normal port.

Therefore, the P85 pin can not be used as programmable I/O port when the INV03 bit is set to 1. When the  $\overline{SD}$  function isn't used, set to 0 (Input) in PD85 and pullup to H in the P85  $\overline{NMI}/\overline{SD}$  pin from outside.